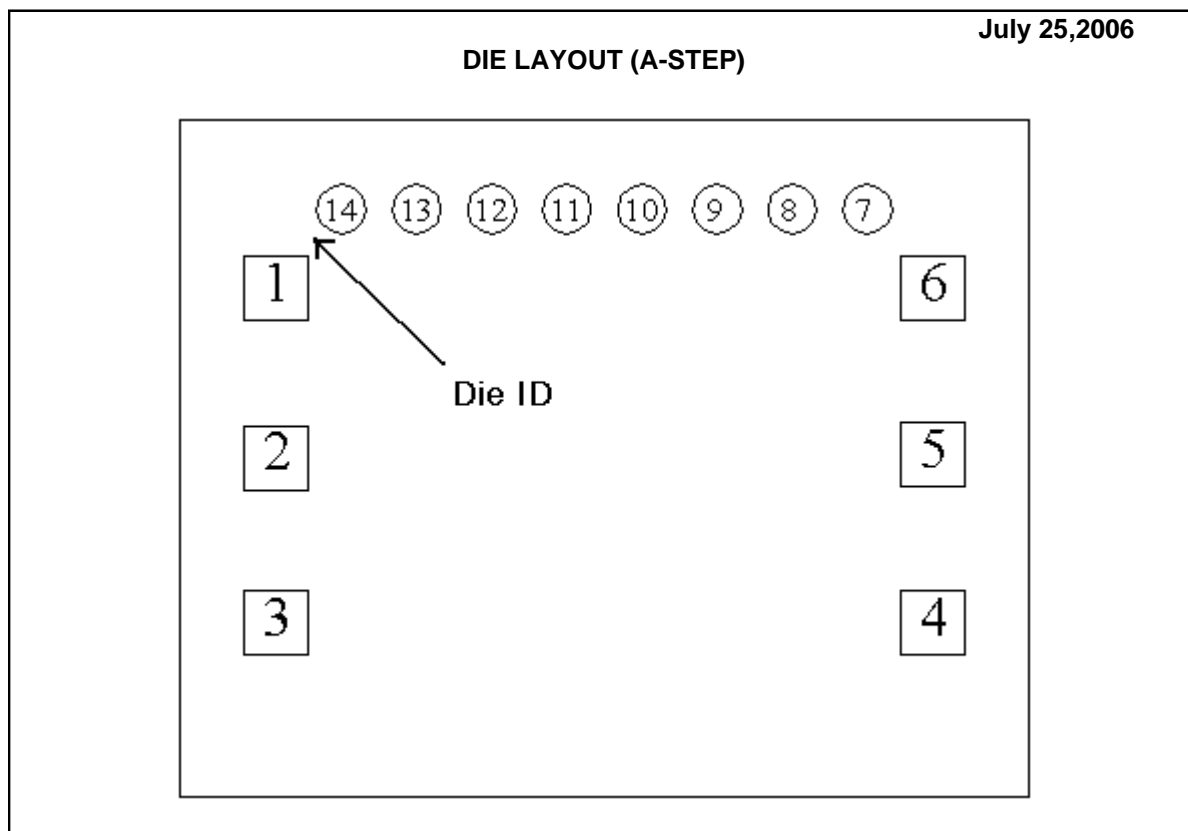


**LM27-2PL MDA MCD2300A**  
**±3°C ACCURATE, 145°C FACTORY PRESET THERMOSTAT WITH ACTIVE HIGH, PUSH/PULL**  
**OVERTEMPERATURE SHUTDOWN OUTPUT**



#### DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM27A	Bond Pad Opening Size (min)	85µm x 85µm
Die Step	A	Bond Pad Metalization	Al_0.5%Cu
Physical Attributes		Passivation	PECVDOX+NITRIDE
Wafer Diameter	200mm	Back Side Metal	BARE BACK
Die Size (Drawn)	1130µm x 902µm 44.5mils x 35.5mils	Back Side Connection	GND
Thickness	254µm Nominal		
Min Pitch	100µm Nominal		

#### Special Assembly Requirements:

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (A -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) <b>NC</b> = No Connection, <b>N.U.</b> = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
HYST	1	-437	225	85	x	85
OS	2	-437	0	85	x	85
NC	3	-437	-220	85	x	85
V+	4	437	-220	85	x	85
GND	5	437	5	85	x	85
V <sub>TEMP</sub>	6	437	225	85	x	85
NC	7	350	331	65	x	65
NC	8	250	331	65	x	65
NC	9	150	331	65	x	65
NC	10	50	331	65	x	65
NC	11	-50	331	65	x	65
NC	12	-150	331	65	x	65
NC	13	-250	331	65	x	65
NC	14	-350	331	65	x	65

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